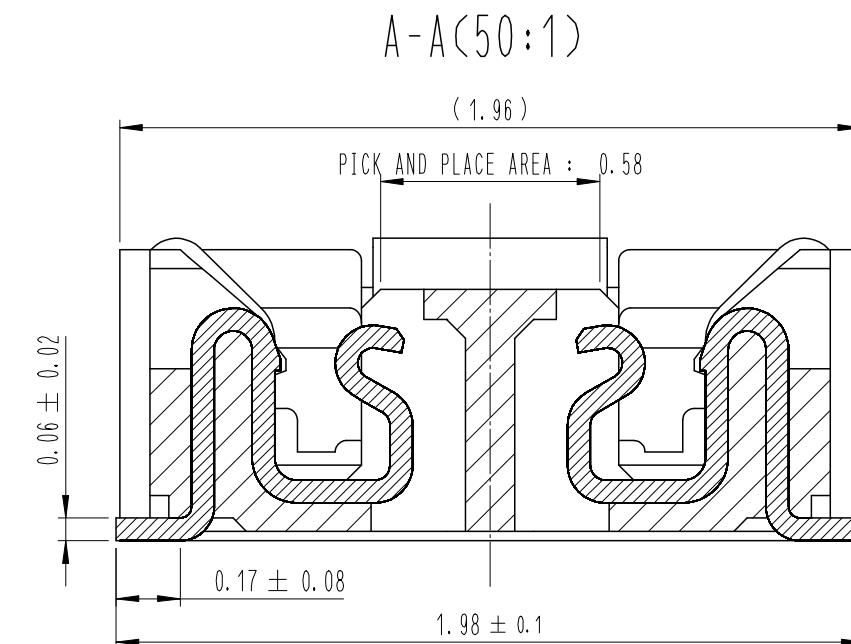


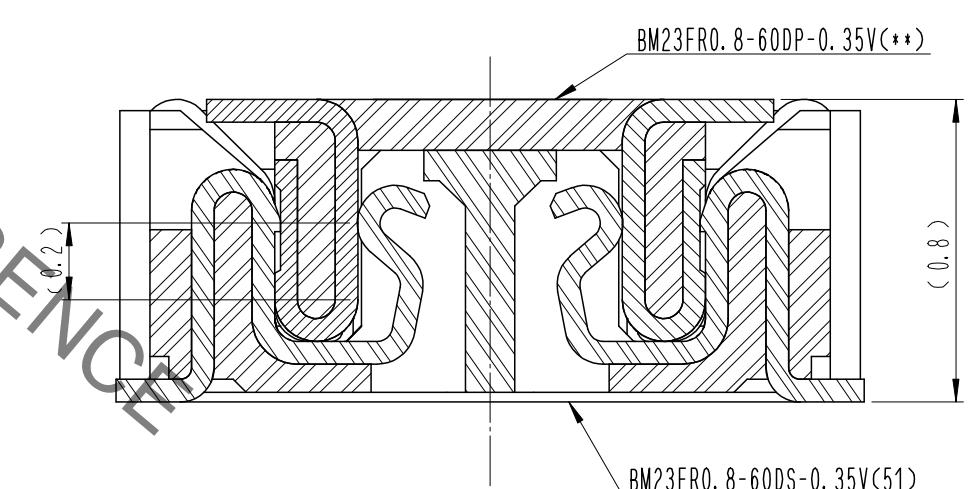
NOTE

- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
- 2. CONTACT PLATING SPECIFICATIONS.  
CONTACT AREA : GOLD 0.05  $\mu\text{m}$  MIN.  
SMT LEAD : GOLD 0.05  $\mu\text{m}$  MIN.  
UNDERPLATING : NICKEL 1  $\mu\text{m}$  MIN.  
( SURFACE : SEALING )
- 3. MATAL FITTING PLATING SPECIFICATIONS.  
SMT LEAD : GOLD 0.05  $\mu\text{m}$  MIN.  
UNDERPLATING : NICKEL 1  $\mu\text{m}$  MIN.  
( SURFACE : SEALING )
- 4. HRS MARK AND CAV NO. IS INDICATED IN APPROX POSITION SHOWN.

COUNT	DESCRIPTION OF REVISIONS			B	Y	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS			B	Y	CHKD	DATE
△	1	Change the bobbin size	LYJ	JHW	15. 12. 03	△		△				△			
△						△		△				△			
△						△		△				△			



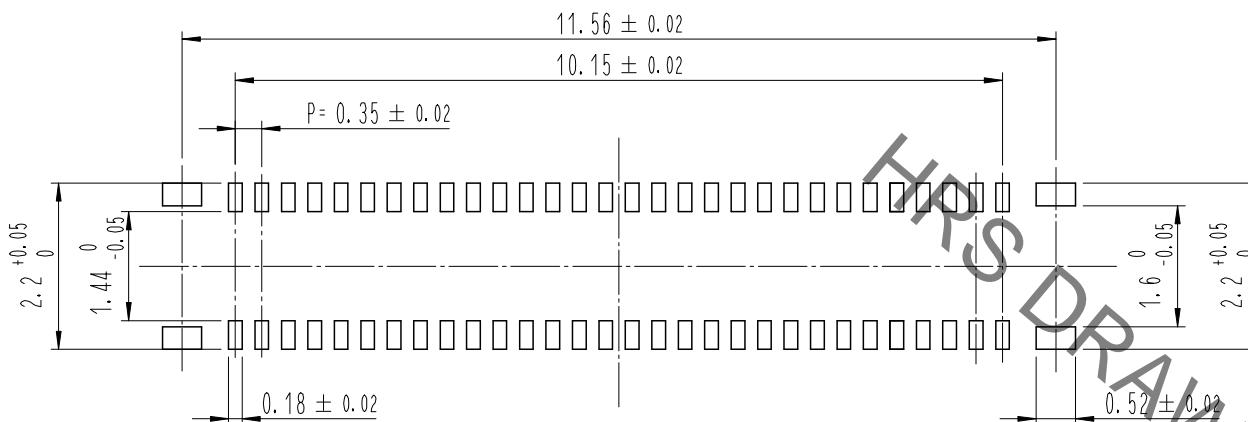
ENGAGEMENT FIGURE (50:1)



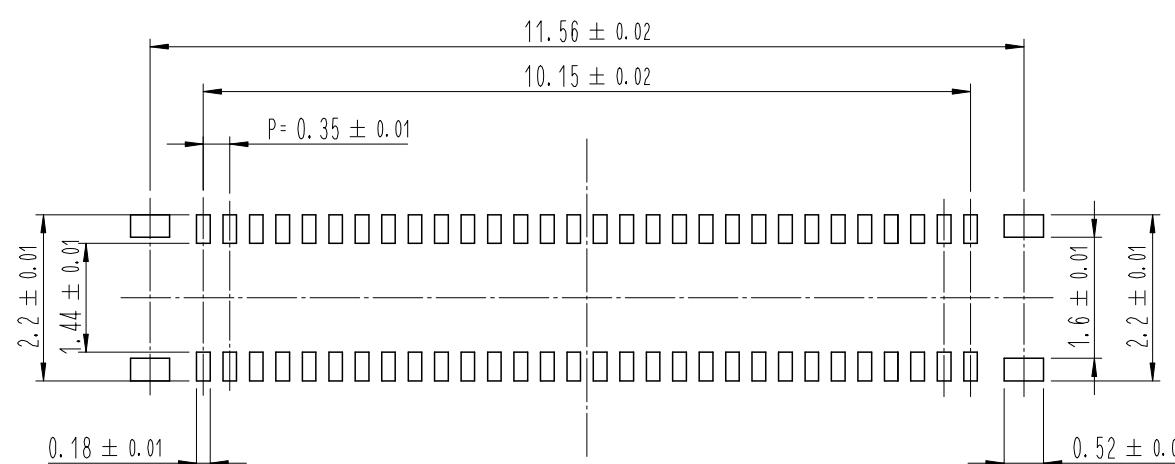
NO.	PS	CLEAR (EMBOSSING CARRIER TAPE)	NO.	PS	BLACK (PLASTIC REEL)
3	PHOSPHOR BRONZE	3	6	PS	BLACK (PLASTIC REEL)
2	PHOSPHOR BRONZE	2	5	POLYESTER	CLEAR (COVER TAPE)
1	LCP	UL94 V-0, BLACK			
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
REMARKS			DRAWN	DESIGNED	CHECKED
			Y. J. LEE	Y. J. LEE	H. W. JO
			15.12.03	15.12.03	15.12.03
CODE NO. (COLD)	SCALE	DRAWING NO.	PART NO.	CODE NO.	1
	10:1	EDC3-632085	BM23FR0.8-60DS-0.35V(51)	CL 6644-0028-3-051	3
	mm				

**HRS** HIROSE KOREA CO., LTD.

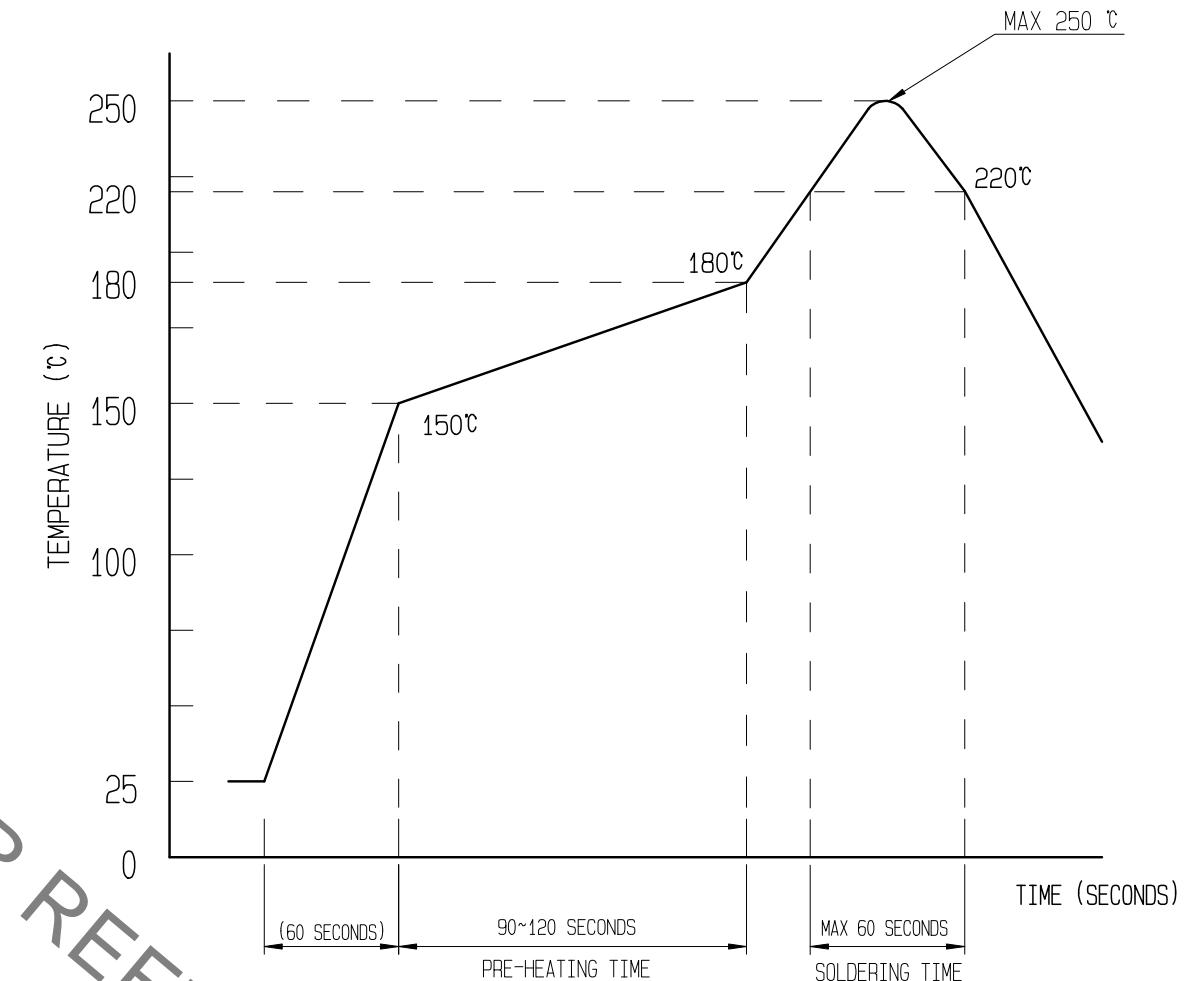
6) RECOMMENDED PCB LAYOUT



RECOMMENDED METAL MASK DIMENSIONS  
METAL MASK THICKNESS : 100  $\mu$ m



5) RECOMMENDED REFLOW TEMPERATURE PROFILE  
USING LEAD-FREE SOLDER PASTE.

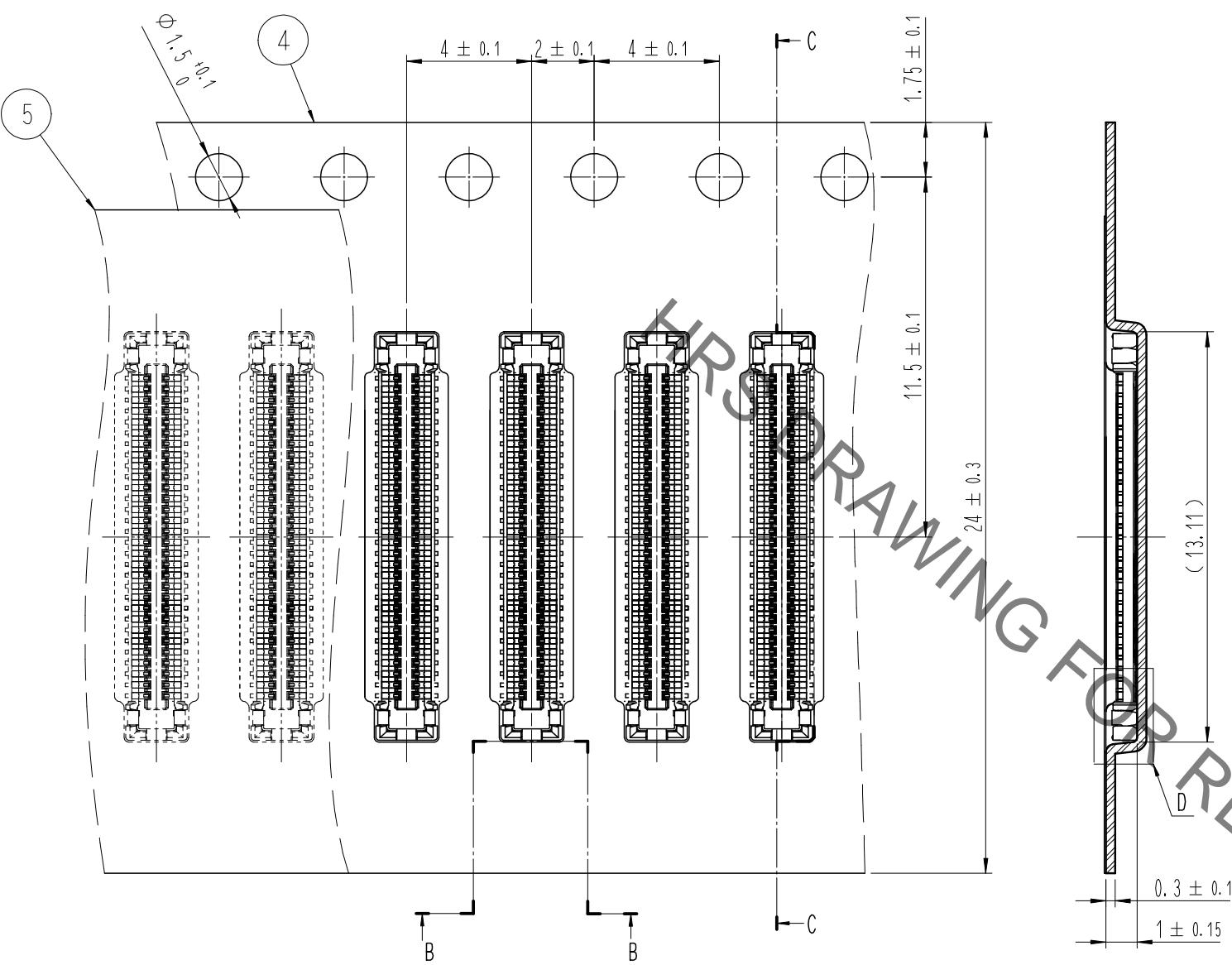


REFLOW METHOD: IR REFLOW  
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.  
1) REFLow TIME  
DURATION ABOVE 220°C, 60 SEC MAX.  
(PEAK TEMPERATURE: 250°C MAX)  
2) PRE-HEAT TIME  
PRE-HEAT TEMPERATURE(MIN): 150°C  
PRE-HEAT TEMPERATURE(MAX): 180°C  
PRE-HEAT TIME: 90-120 SEC.

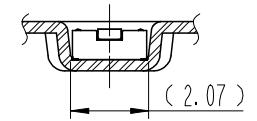
5) THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.  
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND  
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,  
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED  
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.  
6) PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

 <b>SCALE</b> 10:1  <b>UNITS</b> mm	DRAWING NO.	EDC3-632085	PART NO.	BM23FR0.8-60DS-0.35V(51)
	HRS	HIROSE KOREA CO., LTD.	CODE NO	CL 6644-0028-3-051
				2/3

# EMBOSSED CARRIER TAPE PACKAGING (5:1)

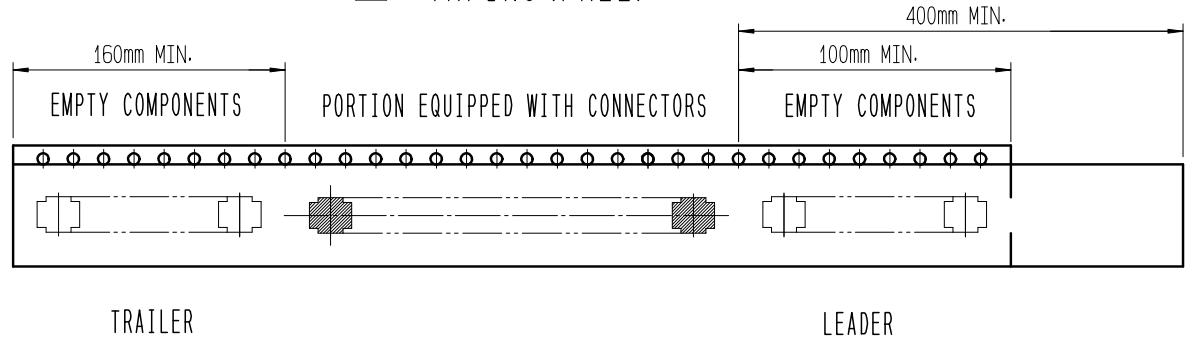


## B-B (5:1)



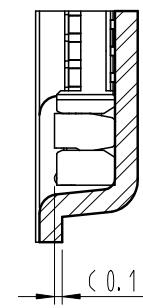
DIRECTION OF UNREELING

400mm MIN.



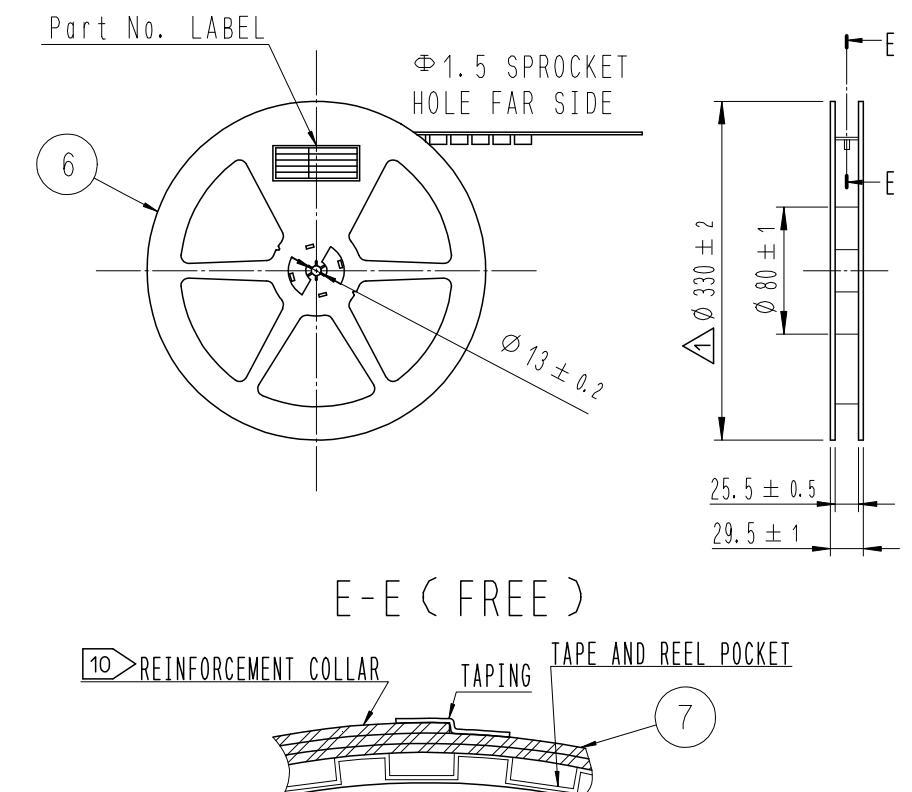
## 9 TAPING(FREE)

## D (10:1)



(0.1)

# STYLE AND DIMENTION OF REEL (FREE)



## DETAIL OF PART No. LABEL

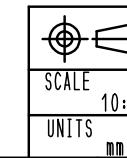
SUPPLIER	HIROSE KOREA
QUANTITY	10,000
PART NO.	BM23FR0.8-60DS-0.35V(51)
CODE NO.	
DATE OF MANUFACTURED	
生産月日	年 月 日
図番	** * * *
品名	BM23FR0.8-60DS-0.35V(51)
納入数量	10,000個
納入者	HIROSE KOREA

7 . PER REEL 10,000 CONNECTORS.

8 . THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

9 . REFER TO JIS C 0806, IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)

10 . AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.



DRAWING NO.  
EDC3-632085

SCALE  
10:1  
UNITS  
mm

PART NO.  
BM23FR0.8-60DS-0.35V(51)

CODE NO.  
CL 6644-0028-3-051

# Mouser Electronics

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